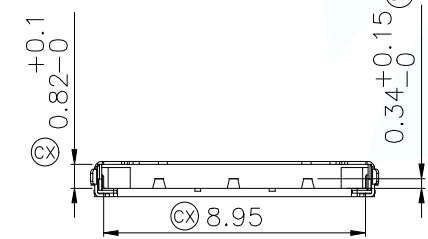
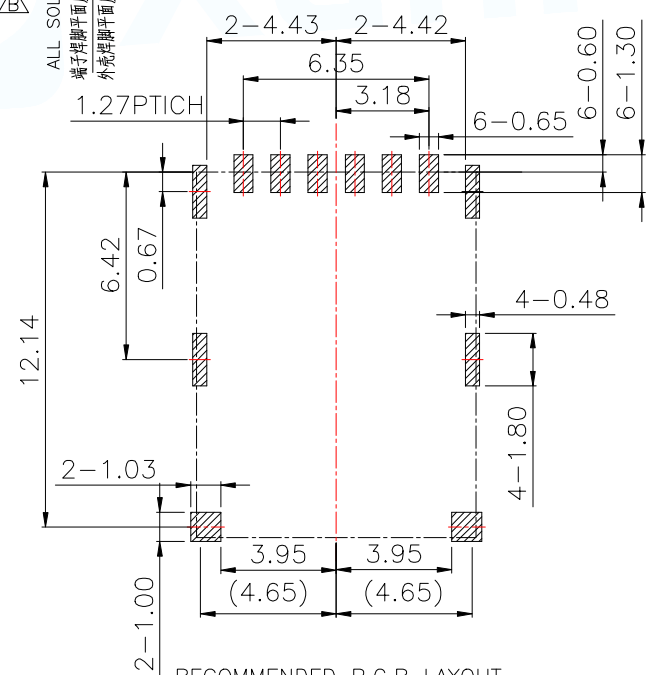


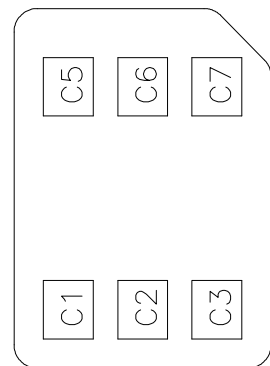
SPECIFICATIONS:  
 1.ELECTRICAL CHARACTERISTICS:  
 1-1.CURRENT RATING:1A  
 1-2.DIELECTRIC WITHSTANDING VOLTAGE:500V R.M.S MIN;  
 1-3.INSULATION RESISTANCE:500MΩMIN.  
 1-4.CONTACT RESISTANCE:100mΩMAX.(INITIAL)  
 2.LIFE TEST: 1500 CYCLES.






ALL SOLDER-TAIL  
 端子焊脚平面度0.06MAX.  
 外壳焊脚平面度0.08MAX.



RECOMMENDED P.C.B LAYOUT  
 TOLERANCE(TOP VIEW) ±0.05mm



NANO SIM CARD PAD

C	SHELL	1	STAINLESS STEEL,0.10T	NICKEL PLATING OVER ALL	
B	CONTACT	1	COPPER ALLOY,0.10T	GOLD FLASH ON CONTACT AREA AND SOLDER AREA 50u" MIN NICKEL UNDER-PLATED.	
A	HOUSING	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK	
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR	
MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES				TITLE: NANO SIM H1.20	
DECIMALS:				PAR	SMN-335-ARP6
ANGLES:				DWN	
.X:±0.20 X':±2°				CHKD	
.XX:±0.10 .X":±1°		APVD			
.XXX:±0.05 .XX":±0.5°		SCALE1:1	UNIT:MM		
CUSTOMER COPY		SIZE:A4	SHEET:1F1	REV:A	